

IN THE SPECIFICATION

Please amend the Specification on third paragraph starting on Page 6, Line 11 as follows:

As shown in the FIG.2C, instead of the adhesive layer 4, silicon 5 can come into contact with the second surface 1b of the first semiconductor chip 1. Here, the adhesive layer 4 can be formed on a top and bottom surface of the silicon 5 4. A dummy wafer sawed to a predetermined size can be used as the silicon 5.